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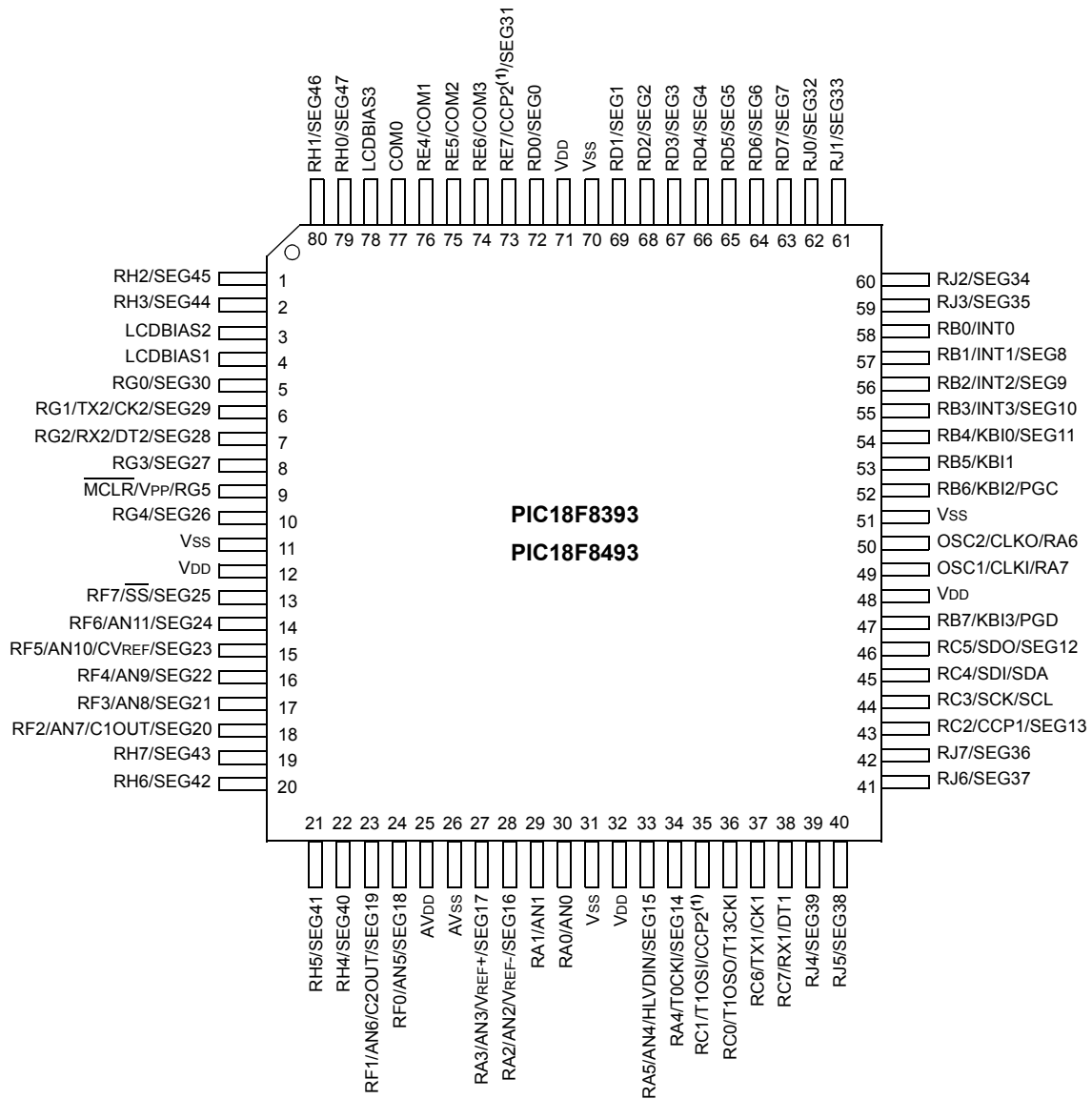
Details

Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, LCD, POR, PWM, WDT
Number of I/O	50
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf6393-i-pt

PIC18F6393/6493/8393/8493

Pin Diagrams (Continued)

80-Pin TQFP



Note 1: RE7 is the alternate pin for CCP2 multiplexing.

PIC18F6393/6493/8393/8493

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PIC18F6393/6493/8393/8493

TABLE 1-1: DEVICE FEATURES

Features	PIC18F6393	PIC18F6493	PIC18F8393	PIC18F8493
Operating Frequency	DC – 40 MHz	DC – 40 MHz	DC – 40 MHz	DC – 40 MHz
Program Memory (Bytes)	8K	16K	8K	16K
Program Memory (Instructions)	4096	8192	4096	8192
Data Memory (Bytes)	768	768	768	768
Interrupt Sources	22	22	22	22
I/O Ports	Ports A, B, C, D, E, F, G	Ports A, B, C, D, E, F, G	Ports A, B, C, D, E, F, G, H, J	Ports A, B, C, D, E, F, G, H, J
Number of Pixels the LCD Driver Can Drive	128 (32 SEGs x 4 COMs)	128 (32 SEGs x 4 COMs)	192 (48 SEGs x 4 COMs)	192 (48 SEGs x 4 COMs)
Timers	4	4	4	4
Capture/Compare/PWM Modules	2	2	2	2
Serial Communications	MSSP, AUSART, Enhanced USART	MSSP, AUSART, Enhanced USART	MSSP, AUSART, Enhanced USART	MSSP, AUSART, Enhanced USART
12-Bit Analog-to-Digital Module	12 Input Channels	12 Input Channels	12 Input Channels	12 Input Channels
Resets (and Delays)	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), MCLR (optional), WDT
Programmable Low-Voltage Detect	Yes	Yes	Yes	Yes
Programmable Brown-out Reset	Yes	Yes	Yes	Yes
Instruction Set	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled
Packages	64-Pin TQFP	64-Pin TQFP	80-Pin TQFP	80-Pin TQFP

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TABLE 1-2: PIC18F6X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
RA0/AN0	24	I/O	TTL	PORTA is a bidirectional I/O port.
RA0		I	Analog	Digital I/O.
AN0				Analog Input 0.
RA1/AN1	23	I/O	TTL	Digital I/O.
RA1		I	Analog	Analog Input 1.
AN1				
RA2/AN2/VREF-/SEG16	22	I/O	TTL	Digital I/O.
RA2		I	Analog	Analog Input 2.
AN2		I	Analog	A/D reference voltage (Low) input.
VREF-		I	Analog	SEG16 output for LCD.
SEG16		O	Analog	
RA3/AN3/VREF+/SEG17	21	I/O	TTL	Digital I/O.
RA3		I	Analog	Analog Input 3.
AN3		I	Analog	A/D reference voltage (High) input.
VREF+		I	Analog	SEG17 output for LCD.
SEG17		O	Analog	
RA4/T0CKI/SEG14	28	I/O	ST	Digital I/O.
RA4		I	ST	Timer0 external clock input.
T0CKI		I	ST	SEG14 output for LCD.
SEG14		O	Analog	
RA5/AN4/HLVDIN/SEG15	27	I/O	TTL	Digital I/O.
RA5		I	Analog	Analog Input 4.
AN4		I	Analog	Low-Voltage Detect input.
HLVDIN		I	Analog	SEG15 output for LCD.
SEG15		O	Analog	
RA6				See the OSC2/CLKO/RA6 pin.
RA7				See the OSC1/CLKI/RA7 pin.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels Analog = Analog input
I = Input O = Output
P = Power I²C = ST with I²C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.
2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

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TABLE 1-2: PIC18F6X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
RF0/AN5/SEG18	18	I/O	ST	PORTF is a bidirectional I/O port.
RF0		I	Analog	Digital I/O.
AN5		O	Analog	Analog input 5.
SEG18		O	Analog	SEG18 output for LCD.
RF1/AN6/C2OUT/SEG19	17	I/O	ST	Digital I/O.
RF1		I	Analog	Analog input 6.
AN6		O	—	Comparator 2 output.
C2OUT		O	Analog	SEG19 output for LCD.
SEG19		O	Analog	
RF2/AN7/C1OUT/SEG20	16	I/O	ST	Digital I/O.
RF2		I	Analog	Analog input 7.
AN7		O	—	Comparator 1 output.
C1OUT		O	Analog	SEG20 output for LCD.
SEG20		O	Analog	
RF3/AN8/SEG21	15	I/O	ST	Digital I/O.
RF3		I	Analog	Analog input 8.
AN8		O	Analog	SEG21 output for LCD.
SEG21		O	Analog	
RF4/AN9/SEG22	14	I/O	ST	Digital I/O.
RF4		I	Analog	Analog input 9.
AN9		O	Analog	SEG22 output for LCD.
SEG22		O	Analog	
RF5/AN10/CVREF/SEG23	13	I/O	ST	Digital I/O.
RF5		I	Analog	Analog input 10.
AN10		O	Analog	Comparator reference voltage output.
CVREF		O	Analog	SEG23 output for LCD.
SEG23		O	Analog	
RF6/AN11/SEG24	12	I/O	ST	Digital I/O.
RF6		I	Analog	Analog input 11.
AN11		O	Analog	SEG24 output for LCD.
SEG24		O	Analog	
RF7/ $\overline{SS}$ /SEG25	11	I/O	ST	Digital I/O.
RF7		I	TTL	SPI™ slave select input.
$\overline{SS}$		O	Analog	SEG25 output for LCD.
SEG25		O	Analog	

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels Analog = Analog input
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Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

PIC18F6393/6493/8393/8493

TABLE 1-3: PIC18F8X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
RH0/SEG47 RH0 SEG47	79	I/O O	ST Analog	PORTH is a bidirectional I/O port. Digital I/O. SEG47 output for LCD.
RH1/SEG46 RH1 SEG46	80	I/O O	ST Analog	Digital I/O. SEG46 output for LCD.
RH2/SEG45 RH2 SEG45	1	I/O O	ST Analog	Digital I/O. SEG45 output for LCD.
RH3/SEG44 RH3 SEG44	2	I/O O	ST Analog	Digital I/O. SEG44 output for LCD.
RH4/SEG40 RH4 SEG40	22	I/O O	ST Analog	Digital I/O. SEG40 output for LCD.
RH5/SEG41 RH5 SEG41	21	I/O O	ST Analog	Digital I/O. SEG41 output for LCD.
RH6/SEG42 RH6 SEG42	20	I/O O	ST Analog	Digital I/O. SEG42 output for LCD.
RH7/SEG43 RH7 SEG43	19	I/O O	ST Analog	Digital I/O. SEG43 output for LCD.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels Analog = Analog input
I = Input O = Output
P = Power I²C = ST with I²C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

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TABLE 1-3: PIC18F8X93 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
RJ0/SEG32 RJ0 SEG32	62	I/O O	ST Analog	PORTJ is a bidirectional I/O port. Digital I/O. SEG32 output for LCD.
RJ1/SEG33 RJ1 SEG33	61	I/O O	ST Analog	Digital I/O. SEG33 output for LCD.
RJ2/SEG34 RJ2 SEG34	60	I/O O	ST Analog	Digital I/O. SEG34 output for LCD.
RJ3/SEG35 RJ3 SEG35	59	I/O O	ST Analog	Digital I/O. SEG35 output for LCD.
RJ4/SEG39 RJ4 SEG39	39	I/O O	ST Analog	Digital I/O. SEG39 output for LCD.
RJ5/SEG38 RJ5 SEG38	40	I/O O	ST Analog	Digital I/O. SEG38 output for LCD.
RJ6/SEG37 RJ6 SEG37	41	I/O O	ST Analog	Digital I/O. SEG37 output for LCD.
RJ7/SEG36 RJ7 SEG36	42	I/O O	ST Analog	Digital I/O. SEG36 output for LCD.
Vss	11, 31, 51, 70	P	—	Ground reference for logic and I/O pins.
VDD	12, 32, 48, 71	P	—	Positive supply for logic and I/O pins.
AVss	26	P	—	Ground reference for analog modules.
AVDD	25	P	—	Positive supply for analog modules.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels Analog = Analog input
I = Input O = Output
P = Power I²C = ST with I²C™ or SMB levels

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.
2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

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The analog reference voltage is software-selectable to either the device's positive and negative supply voltage (AVDD and AVSS), or the voltage level on the RA3/AN3/VREF+/SEG17 and RA2/AN2/VREF-/SEG16 pins.

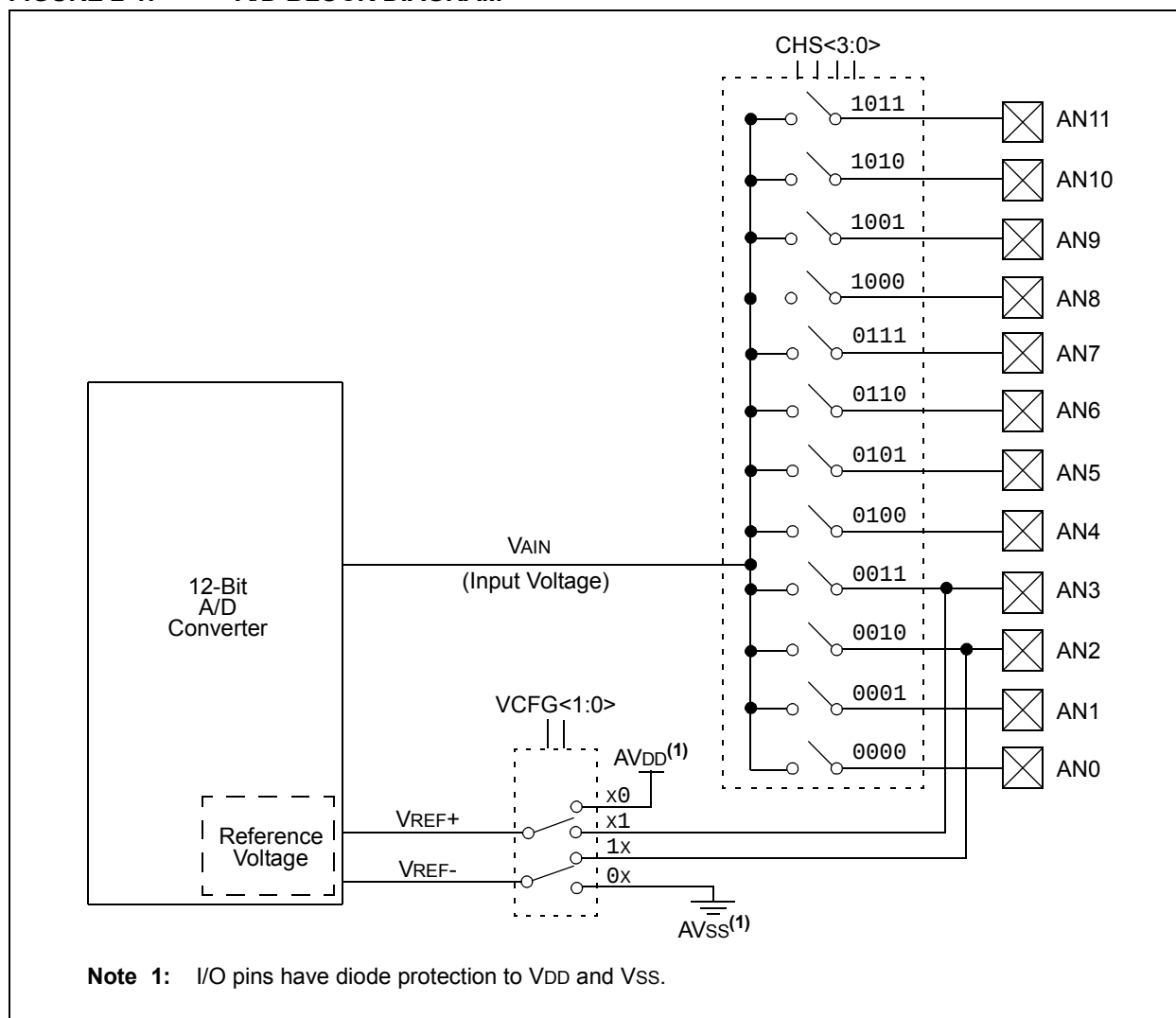
The A/D Converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The output of the sample and hold is the input into the converter, which generates the result via successive approximation.

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D Converter can be configured as an analog input or a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH:ADRESL register pair, the GO/DONE bit (ADCON0<1>) is cleared and the A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 2-1.

FIGURE 2-1: A/D BLOCK DIAGRAM



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The value in the ADRESH:ADRESL registers is unknown following Power-on and Brown-out Resets and is not affected by any other Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see **Section 2.1 “A/D Acquisition Requirements”**. After this acquisition time has elapsed, the A/D conversion can be started. An acquisition time can be programmed to occur between setting the GO/DONE bit and the actual start of the conversion.

The following steps should be followed to perform an A/D conversion:

1. Configure the A/D module:
 - Configure analog pins, voltage reference and digital I/O (ADCON1)
 - Select A/D input channel (ADCON0)
 - Select A/D acquisition time (ADCON2)
 - Select A/D conversion clock (ADCON2)
 - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
 - Clear ADIF bit
 - Set ADIE bit
 - Set GIE bit
3. Wait the required acquisition time (if required).
4. Start conversion:
 - Set GO/DONE bit (ADCON0<1>)

5. Wait for A/D conversion to complete by either:
 - Polling for the GO/DONE bit to be cleared
 OR
 - Waiting for the A/D interrupt
6. Read A/D Result registers (ADRESH:ADRESL); clear bit, ADIF, if required.
7. For the next conversion, go to Step 1 or Step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2 TAD is required before the next acquisition starts.

FIGURE 2-2: A/D TRANSFER FUNCTION

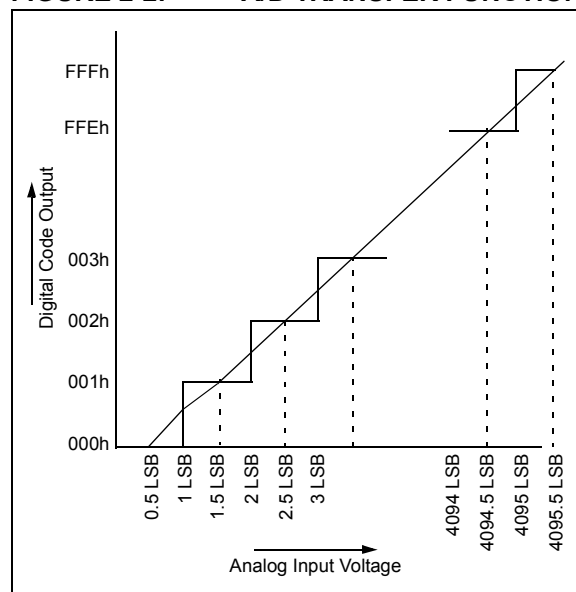
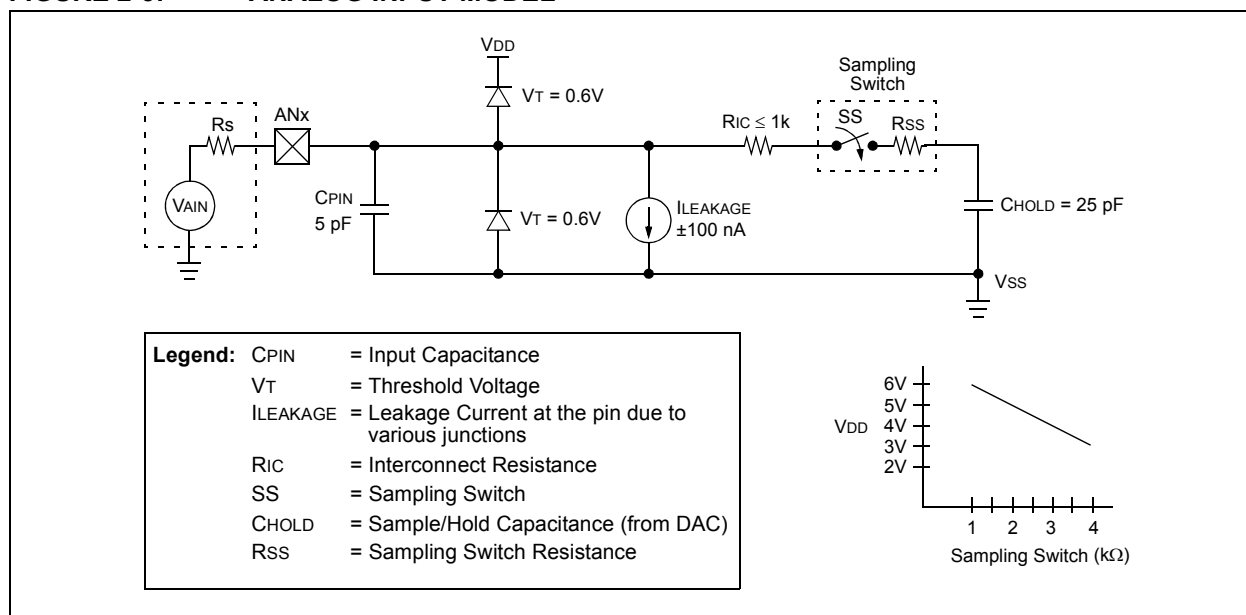


FIGURE 2-3: ANALOG INPUT MODEL



2.2 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set. It also gives users the option to use an automatically determined acquisition time.

Acquisition time may be set with the ACQT<2:0> bits (ADCON2<5:3>), which provide a range of 2 to 20 TAD. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

Manual acquisition is selected when ACQT<2:0> = 000. When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This option is also the default Reset state of the ACQT<2:0> bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

2.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 13 TAD per 12-bit conversion. The source of the A/D conversion clock is software-selectable. There are seven possible options for TAD:

- 2 TOSC
- 4 TOSC
- 8 TOSC
- 16 TOSC
- 32 TOSC
- 64 TOSC
- Internal RC Oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD. (See parameter 130 for more information.)

Table 2-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 2-1: TAD vs. DEVICE OPERATING FREQUENCIES

A/D Clock Source (TAD)		Assumes TAD Min. = 0.8 μ s
Operation	ADCS<2:0>	Maximum Fosc
2 TOSC	000	2.5 MHz
4 TOSC	100	5 MHz
8 TOSC	001	10 MHz
16 TOSC	101	20 MHz
32 TOSC	010	40 MHz
64 TOSC	110	40 MHz
RC ⁽¹⁾	x11	1 MHz ⁽²⁾

Note 1: The RC source has a typical TAD time of 2.5 μ s.

2: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or a Fosc divider should be used instead; otherwise, the A/D accuracy specification may not be met.

2.4 Operation in Power-Managed Modes

If the A/D is expected to operate while the device is in a power-managed mode, the ACQT<2:0> and ADCS<2:0> bits in ADCON2 should be updated in accordance with the clock source to be used in that mode. After entering the mode, an A/D acquisition or conversion may be started. Once started, the device should continue to be clocked by the same clock source until the conversion has been completed.

If desired, the device may be placed into the corresponding Idle mode during the conversion. If the device clock frequency is less than 1 MHz, the A/D RC clock source should be selected.

Operation in Sleep mode requires the A/D FRC clock to be selected. If bits, ACQT<2:0>, are set to '000' and a conversion is started, the conversion will be delayed one instruction cycle to allow execution of the SLEEP instruction, and entry to Sleep mode. The IDLEN bit (OSCCON<7>) must have already been cleared prior to starting the conversion.

2.5 Configuring Analog Port Pins

The ADCON1, TRISA, TRISF and TRISH registers all configure the A/D port pins. The port pins needed as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS<3:0> bits and the TRIS bits.

Note 1: When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Analog conversion on pins configured as digital pins can be performed. The voltage on the pin will be accurately converted.

2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.

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3.0 SPECIAL FEATURES OF THE CPU

Note: For additional details on the Configuration bits, refer to **Section 23.1 “Configuration Bits”** in the “PIC18F6390/6490/8390/8490 Data Sheet” (DS39629). Device ID information presented in this section is for the PIC18F6393/6493/8393/8493 devices only.

PIC18F6393/6493/8393/8493 devices include several features intended to maximize reliability and minimize cost through elimination of external components. These include:

- Device ID Registers

3.1 Device ID Registers

The Device ID registers are “read-only” registers. They identify the device type and revision to device programmers and can be read by firmware using table reads.

TABLE 3-1: DEVICE IDs

File Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default/ Unprogrammed Value
3FFFFEh	DEVID1	DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0	xxxx xxxx ⁽¹⁾
3FFFFFh	DEVID2	DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3	xxxx xxxx ⁽¹⁾

Legend: x = unknown

Note 1: See Register 3-1 and Register 3-2 for DEVID values. DEVID registers are read-only and cannot be programmed by the user.

PIC18F6393/6493/8393/8493

4.0 ELECTRICAL CHARACTERISTICS

Note: Other than some basic data, this section documents only the PIC18F6393/6493/8393/8493 devices' specifications that differ from those of the PIC18F6390/6490/8390/8490 devices. For detailed information on the electrical specifications shared by the PIC18F6393/6493/8393/8493 and PIC18F6390/6490/8390/8490 devices, see the "PIC18F6390/6490/8390/8490 Data Sheet" (DS39629).

Absolute Maximum Ratings^(†)

Ambient temperature under bias	-40°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to V _{SS} (except V _{DD} and $\overline{\text{MCLR}}$)	-0.3V to (V _{DD} + 0.3V)
Voltage on V _{DD} with respect to V _{SS}	-0.3V to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to V _{SS} (Note 2)	0V to +13.25V
Total power dissipation (Note 1)	1.0W
Maximum current out of V _{SS} pin	300 mA
Maximum current into V _{DD} pin	250 mA
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by all ports	200 mA
Maximum current sourced by all ports	200 mA

Note 1: Power dissipation is calculated as follows:

$$\text{PD}_{\text{IS}} = V_{\text{DD}} \times \{I_{\text{DD}} - \sum I_{\text{OH}}\} + \sum \{(V_{\text{DD}} - V_{\text{OH}}) \times I_{\text{OH}}\} + \sum (V_{\text{OL}} \times I_{\text{OL}})$$

- 2:** Voltage spikes below V_{SS} at the $\overline{\text{MCLR}}$ /V_{PP}/RG5 pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$ /V_{PP}/RG5 pin, rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

PIC18F6393/6493/8393/8493

FIGURE 4-1: PIC18F6393/6493/8393/8493 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)

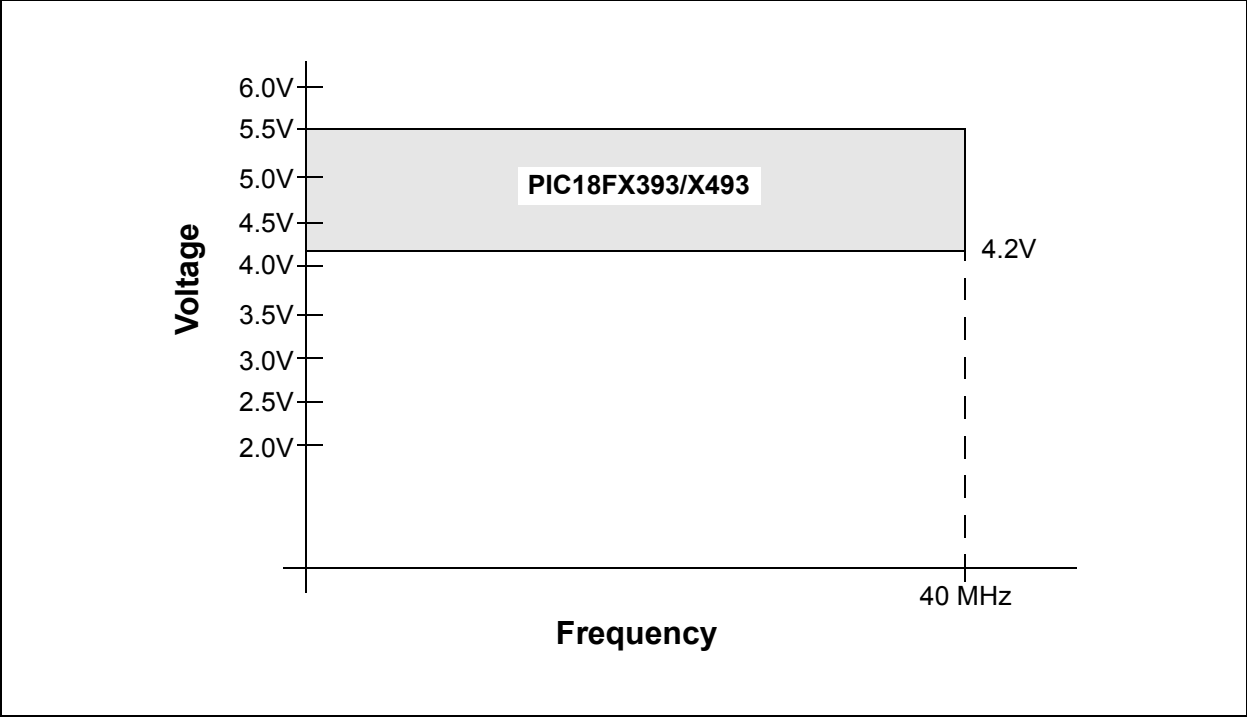
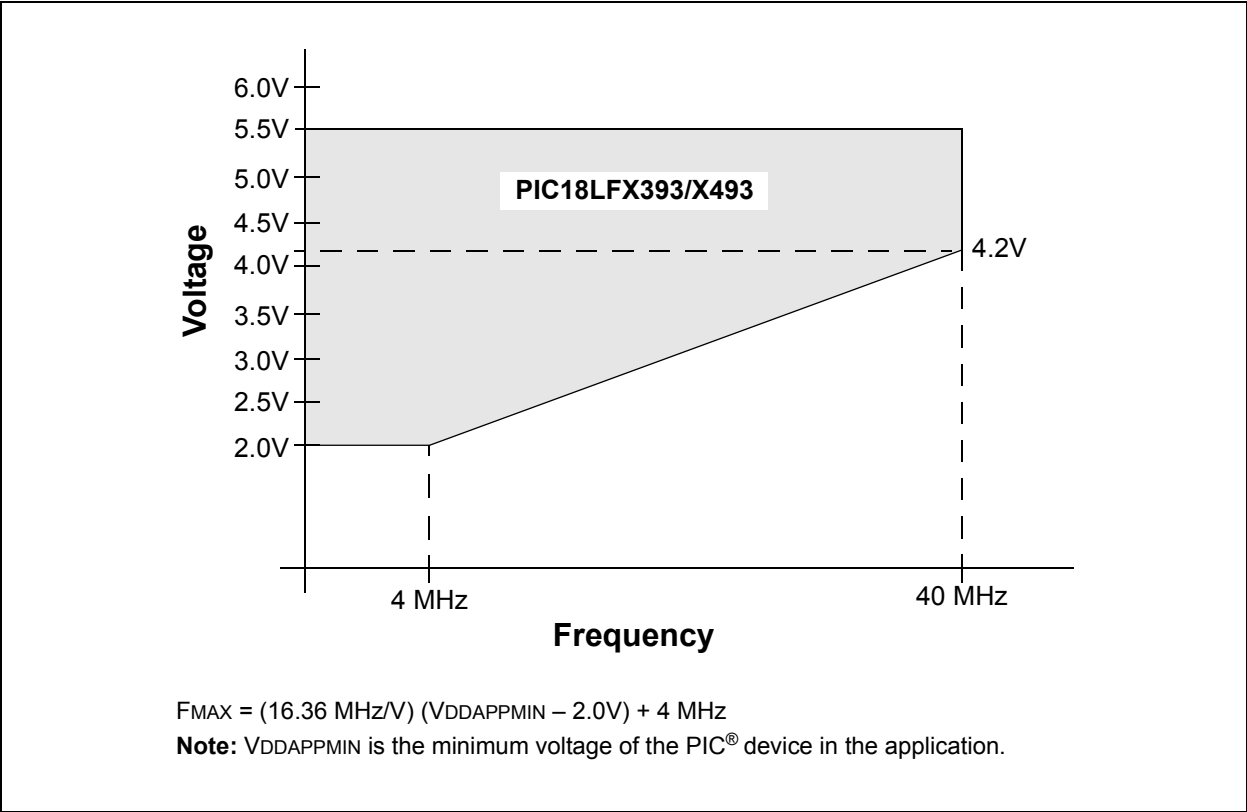


FIGURE 4-2: PIC18LF6393/6493/8393/8493 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



PIC18F6393/6493/8393/8493

TABLE 4-1: A/D CONVERTER CHARACTERISTICS: PIC18F6393/6493/8393/8493 (INDUSTRIAL)

Param No.	Sym	Characteristic	Min	Typ	Max	Units	Conditions
A01	NR	Resolution	—	—	12	bit	$\Delta V_{REF} \geq 3.0V$
A03	EIL	Integral Linearity Error	—	$<\pm 1$	± 2.0	LSB	$V_{DD} = 3.0V$
			—	—	± 2.0	LSB	$V_{DD} = 5.0V$
A04	EDL	Differential Linearity Error	—	$<\pm 1$	$+1.5/-1.0$	LSB	$V_{DD} = 3.0V$
			—	—	$+1.5/-1.0$	LSB	$V_{DD} = 5.0V$
A06	EOFF	Offset Error	—	$<\pm 1$	± 5	LSB	$V_{DD} = 3.0V$
			—	—	± 3	LSB	$V_{DD} = 5.0V$
A07	EGN	Gain Error	—	$<\pm 1$	± 2.00	LSB	$V_{DD} = 3.0V$
			—	—	± 2.00	LSB	$V_{DD} = 5.0V$
A10	—	Monotonicity	Guaranteed ⁽¹⁾			—	$V_{SS} \leq V_{AIN} \leq V_{REF}$
A20	ΔV_{REF}	Reference Voltage Range ($V_{REFH} - V_{REFL}$)	3	—	$V_{DD} - V_{SS}$	V	For 12-bit resolution
A21	V_{REFH}	Reference Voltage High	$V_{SS} + \Delta V_{REF}$	—	V_{DD}	V	For 12-bit resolution
A22	V_{REFL}	Reference Voltage Low	V_{SS}	—	$V_{DD} - \Delta V_{REF}$	V	For 12-bit resolution
A25	V_{AIN}	Analog Input Voltage	V_{REFL}	—	V_{REFH}	V	
A30	Z_{AIN}	Recommended Impedance of Analog Voltage Source	—	—	2.5	k Ω	
A50	I _{REF}	V _{REF} Input Current ⁽²⁾	—	—	5	μA	During V _{AIN} acquisition. During A/D conversion cycle.
			—	—	150	μA	

Note 1: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

Note 2: V_{REFH} current is from the RA3/AN3/ V_{REF+} /SEG17 pin or V_{DD} , whichever is selected as the V_{REFH} source. V_{REFL} current is from the RA2/AN2/ V_{REF-} /SEG16 pin or V_{SS} , whichever is selected as the V_{REFL} source.

APPENDIX C: CONVERSION CONSIDERATIONS

This appendix discusses the considerations for converting from previous versions of a device to the ones listed in this data sheet. Typically, these changes are due to the differences in the process technology used. An example of this type of conversion is from a PIC16C74A to a PIC16C74B.

Not Applicable

APPENDIX D: MIGRATION FROM BASELINE TO ENHANCED DEVICES

This section discusses how to migrate from a Baseline device (i.e., PIC16C5X) to an Enhanced MCU device (i.e., PIC18FXXX).

The following are the list of modifications over the PIC16C5X microcontroller family:

Not Currently Available

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PIC18F6393/6493/8393/8493

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>/XX</u>	<u>XXX</u>
Device	Temperature Range	Package	Pattern
Device ^{(1), (2)}	PIC18F6393, PIC18F6493, PIC18F8393, PIC18F8493 – V _{DD} range: 4.2V to 5.5V PIC18LF6393, PIC18LF6493, PIC18LF8393, PIC18LF8493 – V _{DD} range: 2.0V to 5.5V		
Temperature Range	I	=	-40°C to +85°C (Industrial)
Package	PT	=	TQFP (Thin Quad Flatpack)
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)		

Examples:
a) PIC18LF6393-I/PT 301 = Industrial temp., TQFP package, Extended VDD limits, QTP pattern #301.
b) PIC18LF6393-I/PT = Industrial temp., TQFP package, Extended VDD limits.

Note 1: F = Standard Voltage Range
LF = Wide Voltage Range
2: T = in Tape and Reel TQFP packages only.



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